



P30 Series

Halogen-free Solder Paste

SHENMAO

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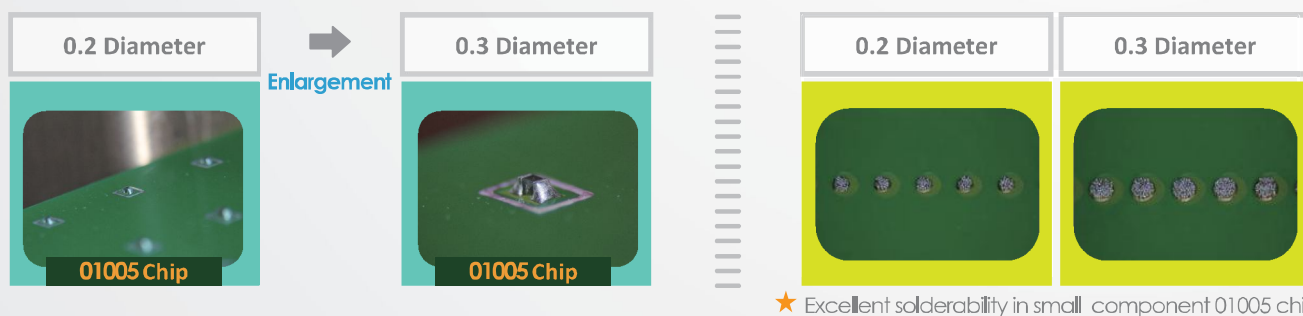


Features

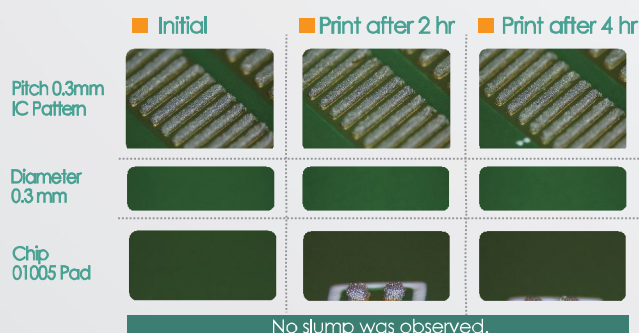
- Excellent void performance
- Lower splattering
- Excellent solderability on ultra fine component
- Excellent printing on ultra fine component



Ultra Fine Component Soldering Performance



Continuous Printing Stability



Lower splattering

Test conditions :

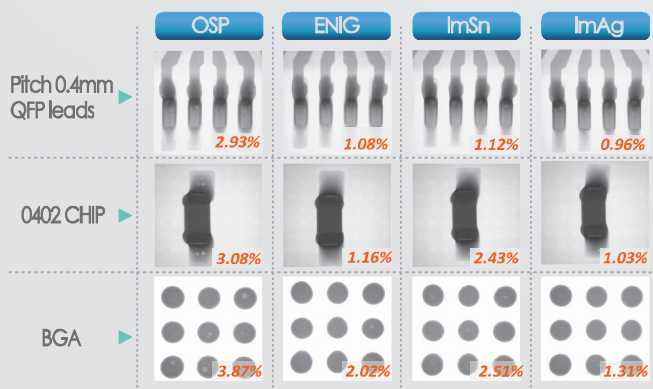
- Surface finish : ENIG
- Stencil thickness : 0.15mm
- Stencil aperture : 6.5mm diameter
- Heating ambient : Air
- Heating profile : Ramp-Soak-Spike



Void performance

Conditions:

- Stencil thickness : 0.12 mm
- Surface finish : OSP/ENIG/ImAg/ImSn
- Printer : Panasonic SP18P-L
- Heating ambient : Air
- Heating profile : Ramp-Soak-Spike



Excellent void performance

Solder Paste	Surface	OSP	ENIG	ImSn	ImAg
P30 Paste		2.93%	1.08%	1.12%	0.96%
Conventional Paste		5.03%	2.15%	2.51%	1.92%



Basic characteristics

Product	Item	Alloy	Melting Point (°C)	Particle Size (μm)
PF606-P30		Sn/Ag3.0/Cu0.5/x	217~219	20~38 20~45
PF629-P30		Sn/Ag0.3/Cu0.7	217~226	20~38 20~45
PF632-P30		Sn/Ag1.0/Cu0.5	217~226	20~38 20~45

Item	Specification	Standard
Flux Content	11.5±1.0wt%	JIS-Z3197, 8.1.2
Viscosity	200±30Pa·s	JIS-Z3284, Annex 6
Flux Type	ROL0	J-STD-004A
Copper Mirror	Pass	IPC-TM-650, 2.3.32
Spreading	> 70%	JIS-Z3197, 8.3.1.1
Slump	Pass	JIS-Z3284, Annex 7, 8
Solder Ball	Pass	JIS-Z3284, Annex 11
S.I.R.	> 1×10 ⁹ Ω, Pass	IPC-TM-650, 2.6.3.3
Electro Migration	Pass	IPC-TM-650, 2.6.14.1